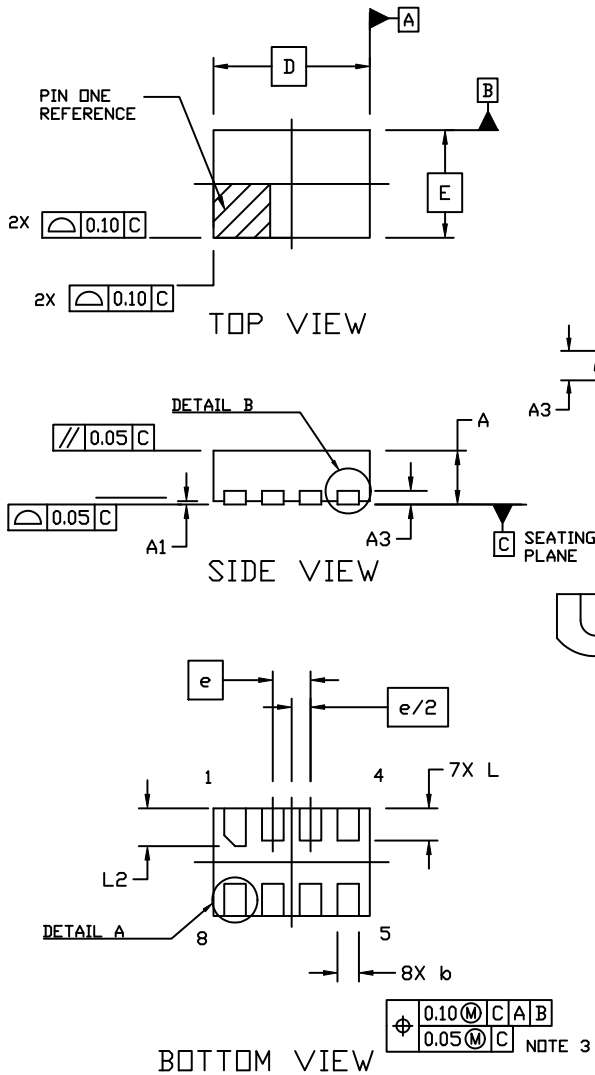


UDFN8, 1.45x1.0, 0.35P
CASE 517EB
ISSUE O

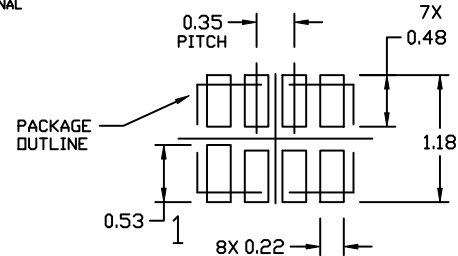
DATE 27 AUG 2018



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION **b** APPLIES TO THE PLATED TERMINALS AND IS MEASURED BETWEEN 0.15 AND 0.20 FROM THE TERMINAL TIPS.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

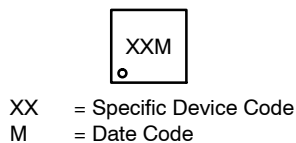
DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	0.45	0.50	0.55
A1	---	---	0.05
A3	0.13 REF		
b	0.15	0.20	0.25
D	1.35	1.45	1.55
E	0.90	1.00	1.10
e	0.35 BSC		
L	0.25	0.30	0.35
L1	0.05	0.10	0.15
L2	0.30	0.35	0.40



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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